



SUA-110H15-30x-S242

鍍層厚度:

Blank : 1u"

2 : 15u"

3 : 30u"

參考的組合圖

RECOMMENDED PCB LAYOUT

NOTE:

1.MATERIAL:

1.1 Housing: PA9T

1.2 Contact: PHOSPHOR BRONZE

1.3 Shell: SUS

2.Finish:

2.1 Contact: Plated Gold in Mating Area ;

Tin Plated on Solder Balls ;

Nickel under plated overall

2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

3.1 Current Rate: 1.8 A

3.2 insulator Resistance:100MΩ Min

3.3 Dielectric Strength: 100V AC

3.4 Contact Resistance: 30mΩ Max

3.5 Operation Temperature: -40°C ~ +85°C

3.6 Insertion Force: 35 N

3.7 Extraction Force: 10 N

Pin #	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS
OTHERWISE STATED :

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 04/22/22
DATE: 04/22/22
DATE: 04/22/22

MATL		TITLE	CONNECTOR
FINISH		MODLE	USB3.0+TYPEC 彎腳 H=15.44mm
SCALE	1 : 1	DWG NO.	SUA-110H15-30x-S242
SHEET NO.	1 of 1	PART NO.	SUA-110H15-30x-S242